

Record of Letter Ballot Review by TC Chapter for Procedural Review

Region/Locale: [Japan](#)

Global Technical Committee: [Silicon Wafer](#)

TC Chapter Cochairs: [T. Nakai /SUMCO](#), [N. Kawai /Meiji University](#)

Standards Staff: [J. Collins](#)

| | Scheduled in Background Statement | Actual |
|--|--|--|
| Date | 12/14/2017 | 12/14/2017 |
| Location | Tokyo Big Sight, Tokyo Japan | Tokyo Big Sight, Tokyo Japan |
| Reason for Change of Date and/or Location (if changed) | | |

Note: See *Regulations* ¶ 9.5 Exception for allowable reason to change.

I. Document Number and Title

| | |
|--|---|
| Document Number 6283 | Document Title REAPPROVAL OF SEMI MF95-1107 (Reapproved 1012) TEST METHOD FOR THICKNESS OF LIGHTLY DOPED SILICON EPITAXIAL LAYERS ON HEAVILY DOPED SILICON SUBSTRATES USING AN INFRARED DISPERSIVE SPECTROPHOTOMETER |
|--|---|

II. Tally

Standards staff to fill in.

Voting Tally: [As-cast tally after close of voting period](#)

Note: A minimum of 60% of the Voting Interests that have TC Members within the global technical committee that issued the Letter Ballot must return Votes. (*Regulations* ¶ 9.7.1.1)

Voting Tally (with example values):

| | | | | | | |
|---------------------------|--------------------|---|---------------------------|---|-----------------------|------|
| Voting Interest: | Returned Votes | | Distribution | | Return Rate | |
| Letter Ballot | 57 | ÷ | 95 | = | 60.0% | ≥60% |
| Intercommittee Ballot | 25 | | | | | |
| | | | | | | |
| Voting Interest Reject(s) | 0 | | Total Voters with Rejects | | 0 | |
| Voting Interest Accept(s) | 30 | | | | | |
| | | | | | | |

Note: See *Regulations* § 3.2.1 for definition of Voting Interest.

III. Rejects: **No Rejects**

IV. Other Technical Issues: **None**

Note: TC Chapter may choose to address a technical issue that is not part of a Negative received on a Letter Ballot (i.e., a Comment or a reason not addressed by a Vote response) by handling it as a Negative and finding it related and technically persuasive. The TC Chapter may then fail the Document or address such technical issue by using the procedure defined in *Regulations* § 9.6.4.3 to make a technical change to the Document. (*Regulations* ¶ 9.6.2.4.5)

V. Comments: **No comments**

VI. Editorial Changes Other than Those Voted on in § V **None**

Original section/paragraph number and at least one full sentence are required in “FROM” and “TO” fields.

VII. Approval Conditions Check

VII. - (i). Approval Rate

APPROVAL CONDITION 1: All Negatives have been discussed and were withdrawn, found not related, found not persuasive, or addressed by a technical change. (*Regulations* ¶ 9.7.1.2)

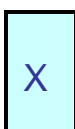
APPROVAL CONDITION 2: At least 90% of the sum of valid Voting Interest Accept and Voting Interest Reject Votes must be Accept. (*Regulations* ¶ 9.7.1.3)

Note: If both approval conditions are not satisfied, the Document fails.

| | | | | | | | | | |
|---------------|---|---------|---|------------------------------|---|--------|--|------|--|
| | | | | | | | | | |
| | | Accepts | | (Accepts + Valid Rejects) | | | | | |
| Approval Rate | = | 30 | / | 30 | = | 100.0% | | ≥90% | |
| | | | | | | | | | |
| | | | | | | | | | |

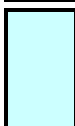
VII. – (ii) Approval Level (**check one**)

Note: See *Regulations* § 9.7.2 for further information.



Globally Approved (No Ratification Ballot needed):

The Letter Ballot meets the Letter Ballot approval conditions for the global technical committee.



Need a Ratification Ballot:

The Letter Ballot meets the Letter Ballot approval conditions for the TC Chapter and a Ratification Ballot will be issued to validate technical changes.

VIII. Safety Check

Note: See Regulations § 15 for further information.

| | | |
|------------------------------|---|--|
| Motion | X | This is not a Safety Document , when all safety-related information is removed, the Document is still technically sound and complete. (<i>Regulations</i> ¶ 8.7.1) |
| | | This is a Safety Document , when all safety-related information is removed, the Document is not technically sound and complete. (<i>Regulations</i> ¶ 8.7.2) |
| | | Safety Checklist (<i>Regulations</i> ¶ 15.3) is complete and has been included with the Document throughout the balloting process. (<i>Regulations</i> ¶ 15.1.2) |
| Motion by/2 nd by | | Ryuji Takeda (GlobalWafers Japan)/ Tsuyoshi Otsuki (SEH) |
| Discussion | | None |
| Vote | | 11 Y-0 N; Motion passed |

IX. Intellectual Property (IP) Check

Note: This Letter Ballot may cover all or part of a Standard or Safety Guideline. This IP check applies to the entire Standard or Safety Guideline. See Regulations § 16 for further information.

| | | |
|--------------|--|---|
| x | The TC Chapter meeting chair asked those participating, if they were aware of any potentially material patented technology or copyrighted items* in the Standard or Guideline. (<i>Regulations</i> ¶ 8.8.1) | |
| Motion | x | No potentially material patented technology or reproduction of copyrighted items is known. GO TO SECTION X. |
| | | Potentially material patented technology or reproduction of copyrighted items is known, but a Letter of Assurance (LOA) or copyright release letter for such items has been obtained or presented to the TC Chapter. GO TO SECTION X. |
| | | Potentially material patented technology or reproduction of copyrighted items is known and use of such materials is technically justified by the TC Chapter, but an LOA or copyright release letter for some of the item(s) has NOT been obtained or presented to the TC Chapter. |
| | | Ask ISC for special permission to publish. |
| | | Quit activity. |
| | | Wait for LOA for patented technology or release of copyrighted items. |
| | Motion by/2 nd by | |
| | Discussion | |
| | Vote | |
| Final Action | | Motion passed |
| | | Motion failed |

*** Note: Such potentially material patented technology or copyrighted items might have become known since the Standard or Safety Guideline was last reviewed, or might become relevant due to this Letter Ballot.**

X. Action for This Document

| | | |
|----------------------------------|-------------------------------------|--|
| Motion | <input checked="" type="checkbox"/> | This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review. |
| | <input type="checkbox"/> | This Document passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review. |
| | <input type="checkbox"/> | This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes. |
| | <input type="checkbox"/> | This Document failed TC Chapter review and will be returned to the TF for rework. |
| | <input type="checkbox"/> | This Document failed TC Chapter review and work will be discontinued. |
| Motion by/ 2 nd by | | Ryuji Takeda (GlobalWafers Japan)/ Tsuyoshi Otsuki (SEH) |
| Discussion | | None |
| Vote | | 11 Y-0 N |
| Final Action | <input checked="" type="checkbox"/> | Motion passed |
| | <input type="checkbox"/> | Motion failed |

Standards staff to record the result of the A&R procedural review here:

| | | |
|-----|--------------------------|--|
| A&R | <input type="checkbox"/> | Approved for publication |
| | <input type="checkbox"/> | Approved pending acceptance of the Ratification Ballot |
| | <input type="checkbox"/> | Not approved |
| | Reason: | |